

Electro-Migration Evaluation System

AEM



The quest for fine pitch pattern and more function

The Electro-Migration Evaluation System AEM Series applies DC current, DC pulsed current, and AC pulsed current under high temperature environment to detect and evaluate the increase of resistance value and leak current caused by electromigration. The system will provide electromigration evaluation indispensable for improving reliability of fine pitched LSIs, flip chip solder ball, and coating material.





MEASUREMENT EVALUATION SYSTEM

ELECTROMIGRATION EVALUATION SYSTEM

LSI ELECTROMIGRATION EVALUATION SYSTEM
GMR HEAD ELECTRO-MIGRATION RH EVALUATION SYSTEM
HIGH FREQUENCY ELECTRO-MIGRATION EVALUATION SYSTEM

TDDB EVALUATION SYSTEM

WAFER LEVEL
PACKAGE LEVEL

SEMICONDUCTOR PARAMETER AUTOMATIC EVALUATION SYSTEM

FET(HOT-CARRIER) PROPERTY EVALUATION SYSTEM
TRANSISTOR PROPERTY EVALUATION SYSTEM

CONDUCTOR RESISTANCE EVALUATION SYSTEM

THROUGH-HOLE CONDUCTOR EVALUATION SYSTEM
SOLDER-JOINT CONTACT EVALUATION SYSTEM
BGA, CSP SOLDER JOINT CONTACT EVALUATION SYSTEM
CONNECTOR CONTACT RESISTANCE EVALUATION SYSTEM
FPC LIFE EVALUATION SYSTEM
OTHER INTERCONNECTION MATERIAL CONTACT
EVALUATION SYSTEM

ION MIGRATION EVALUATION SYSTEM

INSULATION RESISTANCE EVALUATION SYSTEM

CAPACITOR INSULATION RESISTANCE EVALUATION SYSTEM
PCB, PWB INSULATION RESISTANCE EVALUATION SYSTEM
INSULATION RESISTANCE EVALUATION SYSTEM FOR
OTHER INSULATION MATERIAL

LOW-K INSULATION CHARACTERISTIC EVALUATION SYSTEM

LEAK CURRENT MEASUREMENT SYSTEM

CAPACITOR LEAK CURRENT MEASUREMENT SYSTEM
FET LEAK CURRENT MEASUREMENT SYSTEM
SEMICONDUCTOR REVERSE BIAS LEAK CURRENT
MEASUREMENT SYSTEM

CAPACITOR TEMPERATURE PROPERTY EVALUATION SYSTEM

OPTICAL COMPONENT ENVIRONMENTAL TEST SYSTEM

● Six types of stress current

Stress is applied by DC current +, DC current -, DC pulse +, DC pulse -, AC pulse, or AC pulse 0. Test condition can be selected and set individually per 10 channels.

● Three measurement modes

Precision current mode uses precision current generator to measure resistance. Stress-on mode measures resistance while applying stress current. Also equipped with a leak current measurement mode.

● One TEG/one constant-current power supply control

The power source for constant-current stress application is provided on each channel (TEG). Failure will be detected individually on each TEG and stops stress application to the failed TEG.

● Setup of evaluation condition per each TEG board

Evaluation test for 100 TEGs is allowed per chamber. 10 TEGs can be loaded on 1 TEG board, and 10 TEG boards per chamber. Stress current can be set and applied to each TEG board, thus enabling independent testing with different conditions for each board.

● Precise evaluation

Constant current power supply with a stable 3W output, and Kelvin's 4-terminal method realizes high precision measurement.

● Designated chamber with high temperature of + 400

Convection type chamber available with temperatures of +250 and +400.

● Multiple chambers with different settings can be controlled from one AEM system controller.

Temperature setting and test can be controlled for each chamber. The system controller can manage and control the test performed on multiple chambers with different settings.



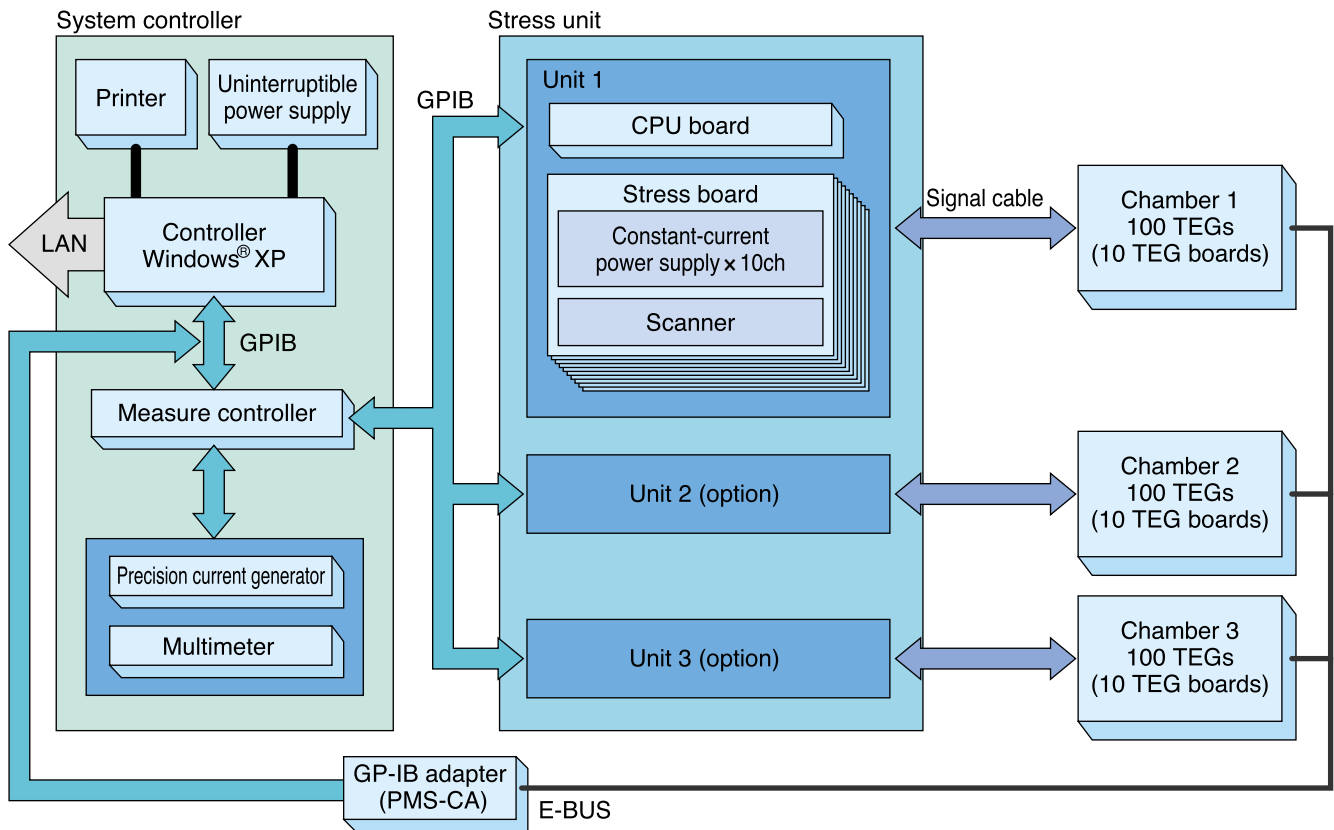
The system is a 100ch. (1 unit) type

APPLICATION

Electro-Migration Evaluation

- Evaluation of LSI fine pitched wiring / copper wiring / aluminum wiring
- Evaluation of flip chip solder ball / UBM
- Evaluation of metal materials which are used under high-density current

SYSTEM BLOCK DIAGRAM



System controller

- Controller : OS Windows® XP (DELL Computer PC)
- Uninterruptable power supply : Backup power supply for controller
- Measure controller : Measurement data acquisition and control
- Precision current generator : Applies constant current during precise resistance measurement
- Digital Multimeter : Measurement of resistance value (Advantest Corp.R-6441C)
- E-BUS : Temperature control of chamber / monitor/ alarm control

Stress unit

- Stress unit : Consists of a CPU board and 10 stress boards
- CPU board : Controls stress board
- Stress board : Scanner & power source for constant current stress, 10 channels per stress board, 1 power source per channel for constant current
- Chamber : High-temperature environment (+250 / +400)

EVALUATION PROCEDURES/ MEASUREMENT MODE

Measurement conditions

Set Duty ratio range 10% to 90% by 10%
 Set pulse repetition frequency
 1Hz, 10Hz, 100Hz, 1KHz, 10KHz

Caution) Stress board for 20mA, 50mA, 1A are a DC constant current and exclusive board

Measurement items

Stress ON resistance measurement

Resistance value is measured while applying stress current. For AC pulse constant current, the larger absolute value is measured. When value reaches the same on both positive and negative side, the positive side is measured.

Precise resistance measurement

Resistance value is measured by cutting off stress current and applying precise current.

Leak current measurement

Leak current between leak terminal and minus terminal is measured after cutting off stress current. (Voltage is constantly applied between the leak terminal and minus terminal)

Various measurement intervals

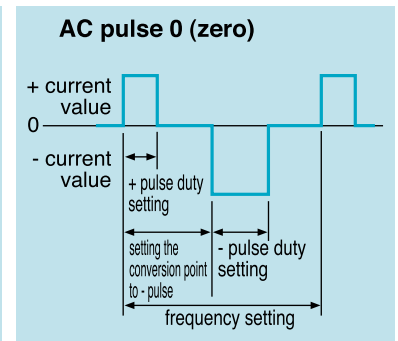
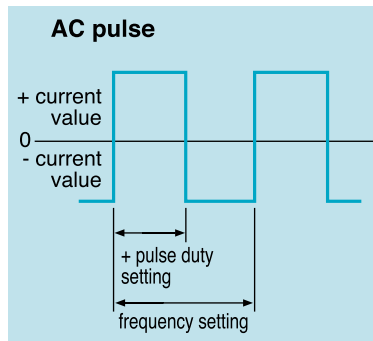
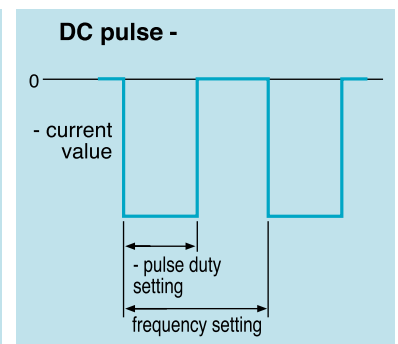
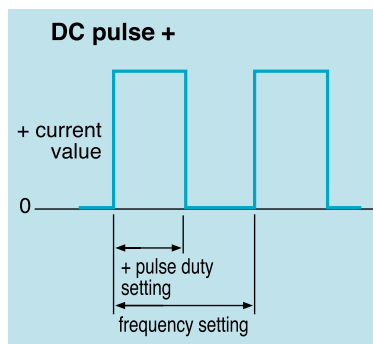
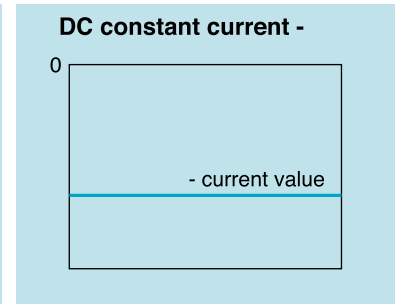
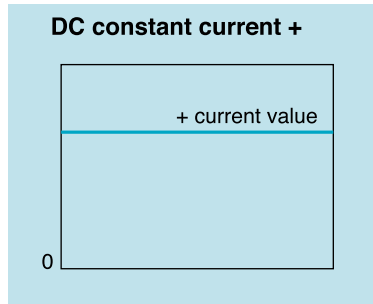
Linear: Measures in equal intervals at setting value by the minute
 (6 to 9,999minutes, per 1 minute)

Log t=0.1: Measured in lapse of 0.1Hr,
 $10^{0.1(n-2)}$ Hr (n=number of times of measurement, n ≥ 2) from test startup.

Log t=1: Measured in lapse of 0.1Hr,
 1Hr, 10Hr, 100Hr, 1000Hr, 10000Hr from test startup.

Block setting: Divided into 3 blocks from test startup to finish. Can be set by intervals mentioned above.

Current stress application mode



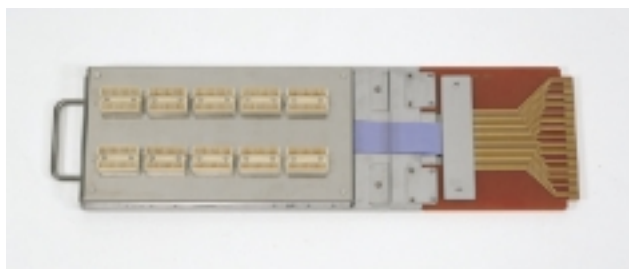
SPECIFICATIONS

Model		AEM-1000
Channel configuration		Standard 100 channels (Maximum 900 channels)
Number of chambers		Controls up to 9 chambers (100 channels per chamber)
Software		Windows® XP
Stress board variation		AC + 50mA/ 50V / 0.01mA in setting steps (optional) AC + 100mA/ 50V / 0.01mA in setting steps DC pulse AC pulse ± 200mA/ 50V/ 0.1mA in setting steps DC pulse AC pulse ± 500mA/ 30V/ 0.1mA in setting steps DC + 1A / 20V / 0.1mA in setting steps (optional) (restricted to maximum of 3W)
Measurement interval		Linear (minimum 6 min.)/ log t = 0.1/log t = 1/ 3-block setting
Open detection		Constant detection of disconnection at less than 1 seconds
Measurement mode	Stress ON measurement	Applicable to all stress boards (Able to set stress migration test)
	Precise current resistance measurement	Measurement current setting range 0.01mA to 100mA (up to 1A is optional)
	Leak current measurement	Applied voltage range - 20V to + 20V (compatible with DC pulse/AC pulse stress board)
Range and accuracy of the stress current (± (0.5%+0.1mA) against set value)		DC pulse/ AC pulse ± 50mA 0.1mA to 50mA ± (0.3%SV + 0.05mA) DC pulse/ AC pulse ± 100mA 0.1mA to 100mA ± (0.3%SV + 0.04mA) DC pulse/ AC pulse ± 200mA 5mA to 200mA ± (0.5%SV + 0.1mA) DC pulse/ AC pulse ± 500mA 5mA to 500mA ± (0.5%SV + 0.1mA) DC + 1A 10mA to 1A (Positive polarity stress only)
Precise resistance measurement		± 0.2% (1mA current value application, at 100 ohms measurement)
Leak current measurement	Applied voltage	DC - 20V to + 20V in 0.1V variable steps
	Measurement range	100pA to 3µA
	Measurement precision	± 5% ± 10nA (at 10M ohms with 20V stress or larger)
System external dimensions (for 300-channel specification)	System controller	650W × 1300H × 800Dmm
	Stress unit	570W × 1830H × 900Dmm
Outside dimension of chamber (excluding protrusions)	+ 250 type	980W × 550H × 890Dmm
	+ 400 type	1015W × 625H × 880Dmm
Required utility (for 100 channels per chamber)	System controller	100V AC ± 10% 50/60Hz 15A
	Stress unit	200V AC ± 10% 50/60Hz 50A
	Chamber (+ 250 spec)	200V AC ± 10% 50/60Hz 20A

TEG board

Type	+ 200 type	+ 250 type	+ 400 type
Material	polyimide substrate	SUS base	
Socket duration	+ 260	+ 260	+ 440
Socket material	heat-resistant resin		ceramics
PIN position	flexible	fixed (can be modified for requirements)	

Caution: Life span of TEG board depends on usage.



The system offers maximum AC pulse at 20MHz/ +350 temperature performance required for Cu evaluation. Networking and control can be easily applied on Windows® XP.

- **Duty ratio can be modified in 10% units**

Offers AC pulse frequency at a maximum 20MHz. The duty ratio can be modified in 10% units between the range of 10 to 90%.

- **Current waveform**

AC probe is equipped on the lower part of the TEG socket to check the current waveform.

(One AC probe is equipped per DHB chamber)

- **Measures resistance by precise constant current power supply**

Resistance is measured by precise constant current power supply. Also equipped with a measurement error improvement mode for further quality performance.

- **Linking DHB chambers**

Up to three DHB chambers can be linked to the controller to set test parameters and start operation. One TEG board can be loaded on one chamber (number of TEGs loaded on one board can be either 10 or 20).

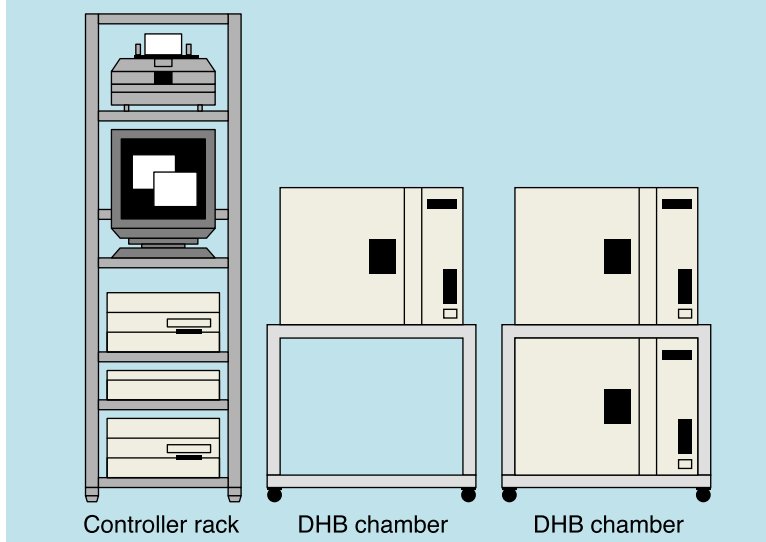
- **+ 350 temperature performance**

With the Direct Heat Board (DHB), precise temperature stress is applied at +350 .

- **Easy operation with Windows® XP**

Control software is applied on Windows® XP. Setting the test parameters and data statistics processing can be done with simple operation. LAN connection to the production line is also possible.

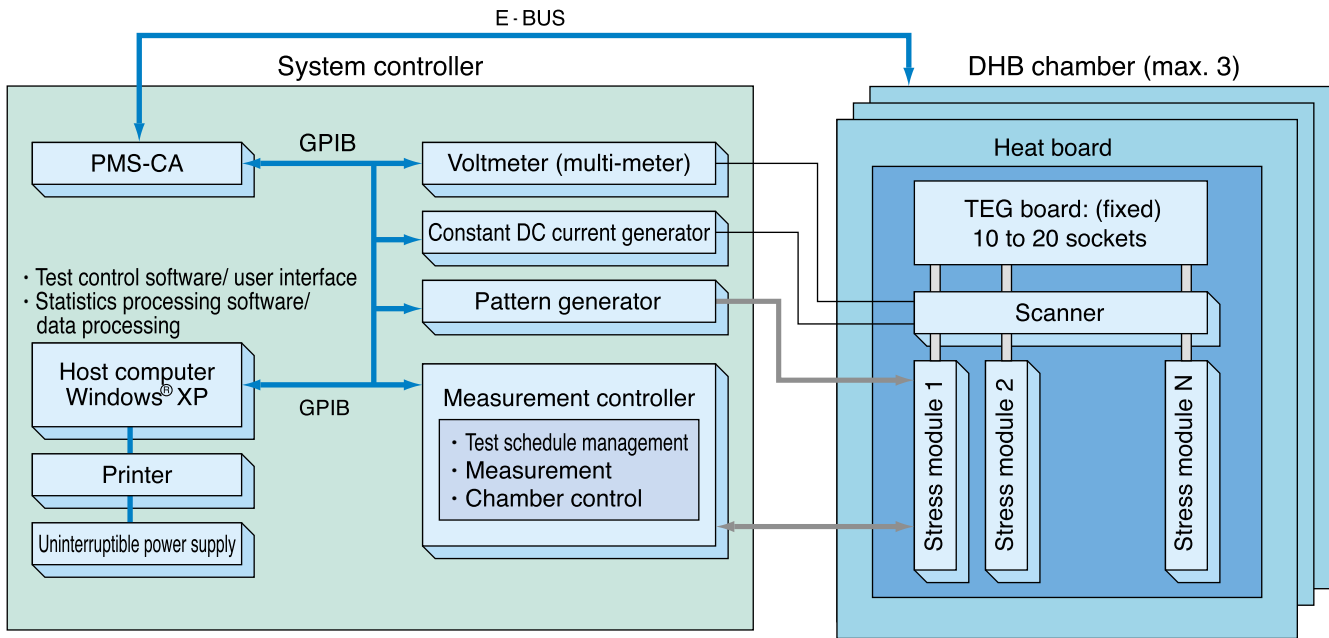
● System Configuration



APPLICATION

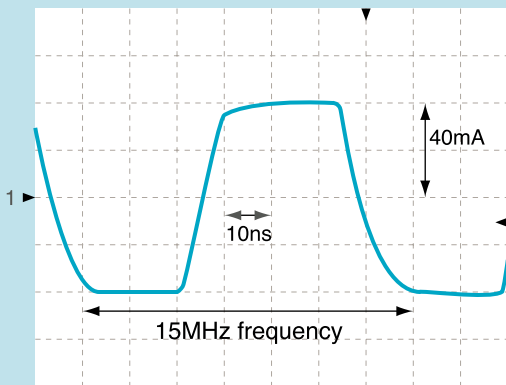
**Wiring migration evaluation of semi-conductor process
Simulation by high frequency application**

SYSTEM BLOCK DIAGRAM



CURRENT WAVEFORM AND RESISTANCE VALUE

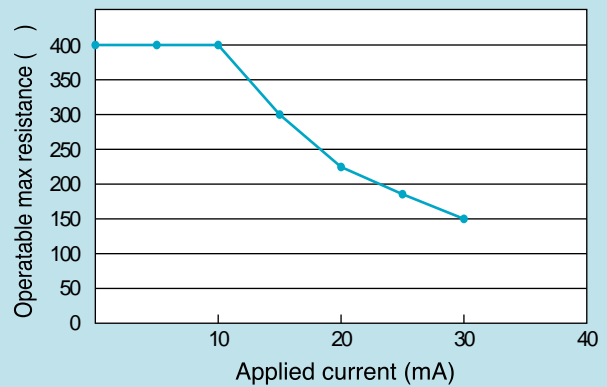
● AC Pulse Constant Current Waveform



Condition	Resistance	51
	Applied current	40mA
	Repeated frequency	15MHz

● Applied Current and Resistance Value Sample

Maximum applicable voltage = Below graph shows regulation on operatable maximum resistance value (R_{max}) from 4.5V.
Measured maximum resistance value = 400



SPECIFICATIONS

Model		AEM-HF
Software		Windows® XP + Visual Basic
AC pulse constant current application range		0.1mA to 30mA (at plus/minus) Setting resolution of current rate 3mA range: 0.01mA (10µA) 30mA range: 0.03mA (30µA)
AC pulse frequency		100KHz to 20MHz (minimum pulse width 25ns)
Set DUTY ratio range		10 to 90 % (at 10% range setting)
Other stress power source		DC pulse constant current/ DC constant current (optional)
Measurement precision		±0.2% (applied currency 1mA/ at 100)
No. of TEGs		10 or 20 TEGs (for one DHB chamber)/ up to 3 chambers
Test temperature range		+ 70 to + 350 (temperature uniformity ±7 at + 350)
Required utility		200V AC 20A (for one DHB Chamber) 100V AC 15A (controller rack)
Outside dimension of system	DHB chamber	1066W × 670H × 745Dmm
	System controller	530W × 1800H × 1100Dmm

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